

Form PTO-1449 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	ATTY. DKT. NO. 219.40605X00	SERIAL NO. 10/695,328 10/066,643
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U.S. PATENT DOCUMENTS Oct. 27/2003

Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date
	AA					
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FOREIGN PATENT DOCUMENTS

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						Yes	No
	AM						
	AN						
	AO						
	AP						
	AQ						
	AR						
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	AT						

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

BE0	AU	"Ultra Thin Electronics for Space Applications", 2001 Electronic Components and Technology Conference, 2001 IEEE
BE0	AV	"Copper Wafer Bonding"; A. Fan, A. Rahman, and R. Reif; Electrochemical and Solid-State Letters, 2 (10):534-536 (1999)
BE0	AW	"Face to Face Wafer Bonding for 3D Chip Stack Fabrication to Shorten Wire Lengths", June 27-29, 2000 VMIC Conference 2000 IMIC - 200/00/0090(c)
BE0	AX	"InterChip Via Technology for Vertical System Integration", Fraunhofer Institute for Reliability and Microintegration, Munich, Germany; Infineon Technologies AG, Munich, Germany; 2001 IEEE
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Examiner Beth E. Owens		Date Considered 6.23.04